

PACKAGED MICROELECTRONIC IMAGERS AND METHODS OF PACKAGING
MICROELECTRONIC IMAGERS

ABSTRACT OF THE DISCLOSURE

Microelectronic imagers and methods of packaging microelectronic imagers are disclosed herein. In one embodiment, a microelectronic imager can include a microelectronic die, an image sensor, an integrated circuit electrically coupled to the image sensor, and a plurality of terminals electrically coupled to the integrated circuit. The microelectronic imager can further include a single unitary member cover unit having a window and a side member projecting from the window. The side member is attached to the die. A plurality of electrically conductive interconnects can extend through the microelectronic die and/or the cover unit and are electrically coupled to corresponding terminals. The microelectronic imager can further include an optics unit having an optic member attached to the cover unit, with the optic member positioned at a desired location relative to the image sensor.